

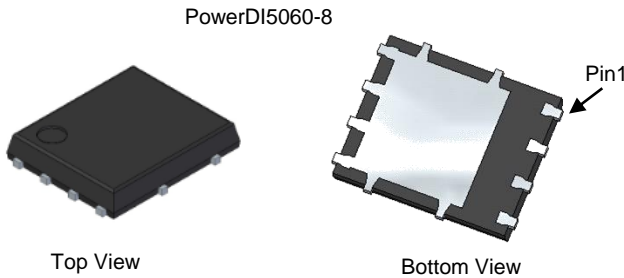
**Product Summary**

|                         |                               |   |
|-------------------------|-------------------------------|---|
| <b>BV<sub>DSS</sub></b> | <b>R<sub>DS(ON)</sub> MAX</b> | <b>I<sub>D</sub> MAX</b><br><b>T<sub>C</sub> = +25°C</b><br><b>(Note 9)</b> |
| 60V                     | 3.1mΩ @ V <sub>GS</sub> = 10V | 100A  |

**Description and Applications**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Switching
- Synchronous Rectification
- DC-DC Converters

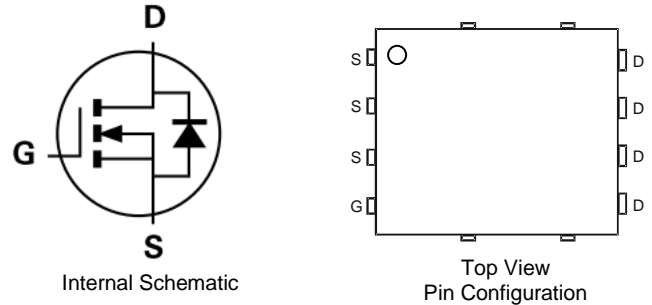


**Features**

- 100% Unclamped Inductive Switching (UIS) Test in Production – Ensures More Reliable And Robust End Application
- Low R<sub>DS(ON)</sub> – Minimizes Power Losses
- Low Q<sub>g</sub> – Minimizes Switching Losses
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. “Green” Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](https://www.diodes.com/quality/product-definitions/) or your local Diodes representative.**  
<https://www.diodes.com/quality/product-definitions/>

**Mechanical Data**

- Case: PowerDI<sup>®</sup>5060-8
- Case Material: Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208@3
- Weight: 0.097 grams (Approximate)

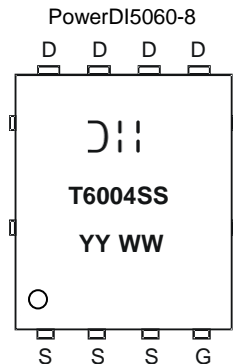


**Ordering Information** (Note 4)

| Part Number   | Case          | Packaging           |
|---------------|---------------|---------------------|
| DMT6004SPS-13 | PowerDI5060-8 | 2,500 / Tape & Reel |

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information**



D||| = Manufacturer's Marking  
 T6004SS = Product Type Marking Code  
 YYWW = Date Code Marking  
 YY = Year (ex: 21 = 2021)  
 WW = Week (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated.

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic  |              |                        | Symbol           | Value | Unit |
|---|--------------|------------------------|------------------|-------|------|
| Drain-Source Voltage  |              |                        | V <sub>DSS</sub> | 60    | V    |
| Gate-Source Voltage   |              |                        | V <sub>GSS</sub> | ±20   | V    |
| Continuous Drain Current (Note 5)                               | Steady State | T <sub>A</sub> = +25°C | I <sub>D</sub>   | 23    | A    |
|   |              | T <sub>A</sub> = +70°C |                  | 18    |      |
| Continuous Drain Current (Notes 6 & 9)                          |              | T <sub>C</sub> = +25°C | I <sub>D</sub>   | 100   | A    |
|   |              | T <sub>C</sub> = +70°C |                  | 100   |      |
| Maximum Continuous Body Diode Forward Current (Notes 6 & 9)     |              |                        | I <sub>S</sub>   | 100   | A    |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)              |              |                        | I <sub>DM</sub>  | 400   | A    |
| Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%) |              |                        | I <sub>SM</sub>  | 400   | A    |
| Avalanche Current, L = 0.2mH                                    |              |                        | I <sub>AS</sub>  | 45    | A    |
| Avalanche Energy, L = 0.2mH                                     |              |                        | E <sub>AS</sub>  | 200   | mJ   |

**Thermal Characteristics**

| Characteristic                          |                        | Symbol                            | Value       | Unit |
|---|------------------------|-----------------------------------|-------------|------|
| Total Power Dissipation (Note 5)        | T <sub>A</sub> = +25°C | P <sub>D</sub>                    | 2.6         | W    |
| Thermal Resistance, Junction to Ambient | Steady State           | R <sub>θJA</sub>                  | 47          | °C/W |
| Total Power Dissipation (Note 6)        | T <sub>C</sub> = +25°C | P <sub>D</sub>                    | 139         | W    |
| Thermal Resistance, Junction to Case    |                        | R <sub>θJC</sub>                  | 0.9         | °C/W |
| Operating and Storage Temperature Range |                        | T <sub>J</sub> , T <sub>STG</sub> | -55 to +150 | °C   |

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                          | Symbol              | Min | Typ   | Max  | Unit | Test Condition  |
|---|---------------------|-----|-------|------|------|---|
| <b>OFF CHARACTERISTICS (Note 7)</b>     |                     |     |       |      |      |   |
| Drain-Source Breakdown Voltage          | BV <sub>DSS</sub>   | 60  | —     | —    | V    | V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA  |
| Zero Gate Voltage Drain Current         | I <sub>DSS</sub>    | —   | —     | 1    | µA   | V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V   |
| Gate-Source Leakage                     | I <sub>GSS</sub>    | —   | —     | ±100 | nA   | V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V  |
| <b>ON CHARACTERISTICS (Note 7)</b>      |                     |     |       |      |      |   |
| Gate Threshold Voltage                  | V <sub>GS(TH)</sub> | 2   | 2.5   | 4    | V    | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250µA                                |
| Static Drain-Source On-Resistance       | R <sub>DS(ON)</sub> | —   | —     | 3.1  | mΩ   | V <sub>GS</sub> = 10V, I <sub>D</sub> = 50A   |
| Diode Forward Voltage                   | V <sub>SD</sub>     | —   | 0.9   | 1.2  | V    | V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A  |
| <b>DYNAMIC CHARACTERISTICS (Note 8)</b> |                     |     |       |      |      |   |
| Input Capacitance                       | C <sub>iss</sub>    | —   | 4,556 | —    | pF   | V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V, f = 1MHz                                     |
| Output Capacitance                      | C <sub>oss</sub>    | —   | 1,383 | —    |      |   |
| Reverse Transfer Capacitance            | C <sub>rss</sub>    | —   | 105.2 | —    |      |   |
| Gate Resistance                         | R <sub>g</sub>      | —   | 0.7   | —    | Ω    | V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz                                      |
| Total Gate Charge                       | Q <sub>g</sub>      | —   | 95.4  | —    | nC   | V <sub>DD</sub> = 30V, I <sub>D</sub> = 90A, V <sub>GS</sub> = 10V                        |
| Gate-Source Charge                      | Q <sub>gs</sub>     | —   | 21.6  | —    |      |   |
| Gate-Drain Charge                       | Q <sub>gd</sub>     | —   | 20.4  | —    |      |   |
| Turn-On Delay Time                      | t <sub>D(ON)</sub>  | —   | 13.2  | —    | ns   | V <sub>DD</sub> = 30V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 90A, R <sub>g</sub> = 3.5Ω |
| Turn-On Rise Time                       | t <sub>r</sub>      | —   | 11.7  | —    |      |   |
| Turn-Off Delay Time                     | t <sub>D(OFF)</sub> | —   | 31    | —    |      |   |
| Turn-Off Fall Time                      | t <sub>f</sub>      | —   | 12    | —    |      |   |
| Body Diode Reverse Recovery Time        | t <sub>RR</sub>     | —   | 50.5  | —    | ns   | I <sub>F</sub> = 50A, di/dt = 100A/µs   |
| Body Diode Reverse Recovery Charge      | Q <sub>RR</sub>     | —   | 80.8  | —    | nC   |   |

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
  - Thermal resistance from junction to soldering point (on the exposed drain pad).
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to production testing.
  - Package limited.

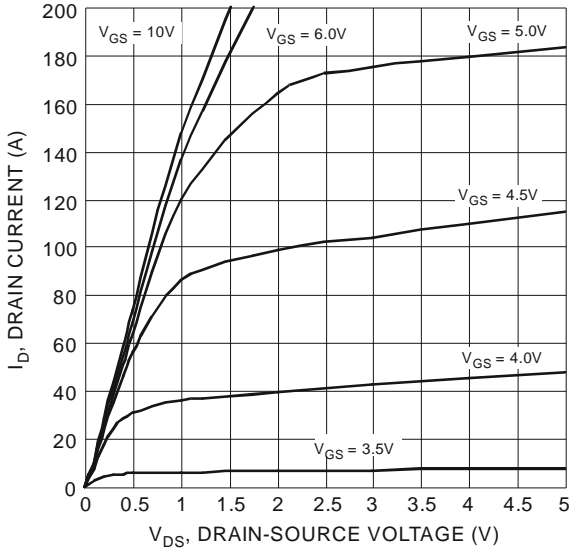


Figure 1 Typical Output Characteristics

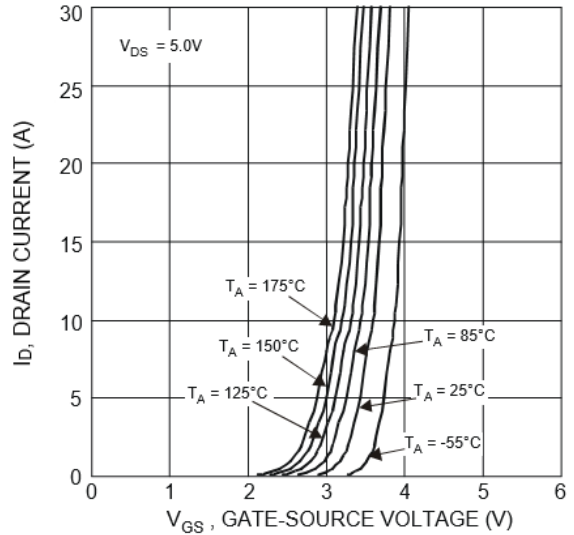


Figure 2 Typical Transfer Characteristics

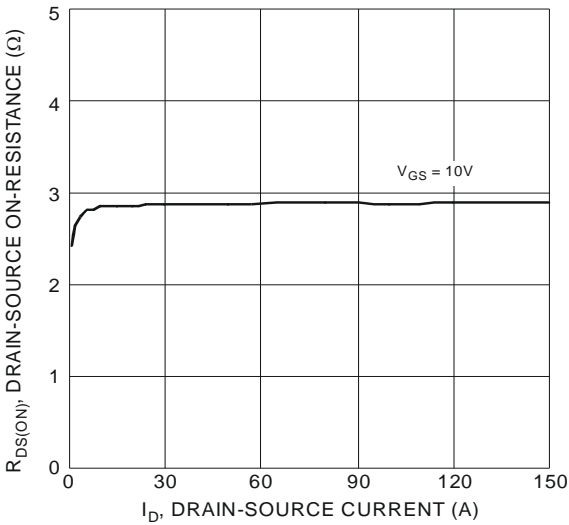


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

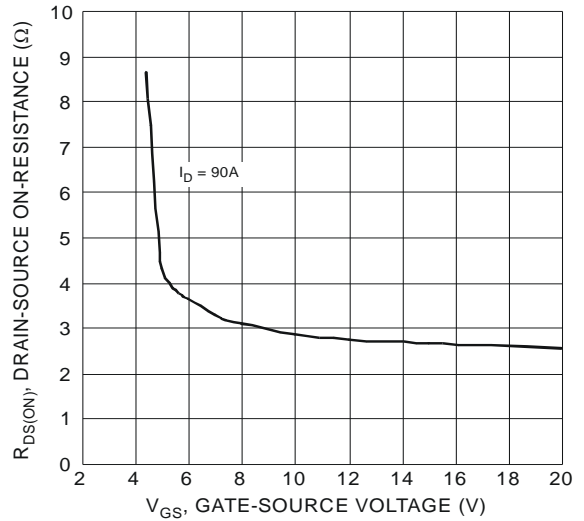


Figure 4 Typical Drain-Source On-Resistance vs. Gate-Source Voltage

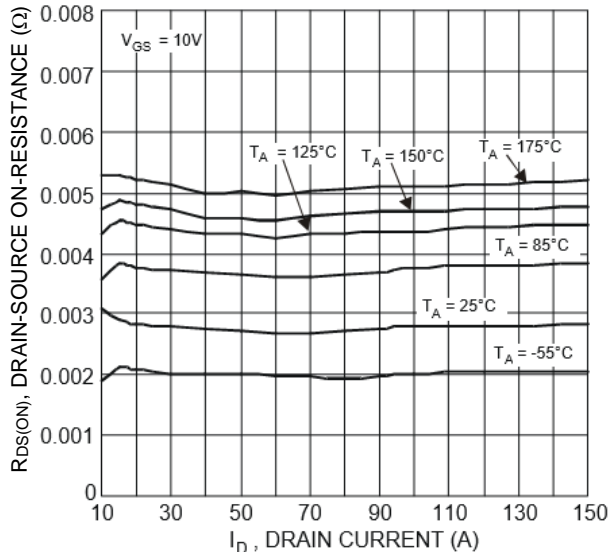


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

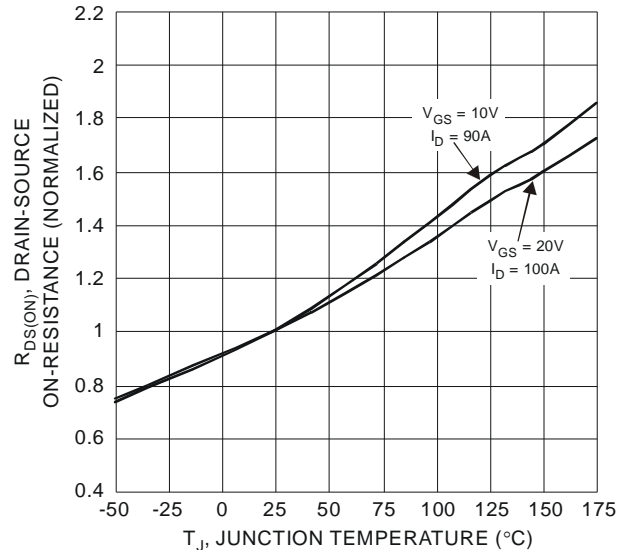


Figure 6 On-Resistance Variation with Temperature

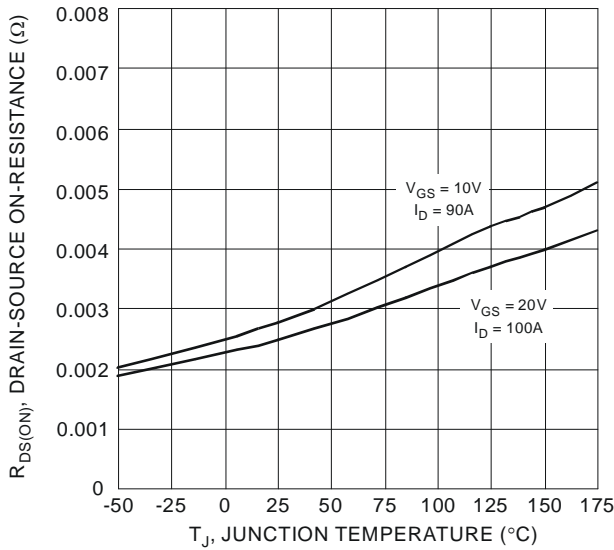


Figure 7 On-Resistance Variation with Temperature

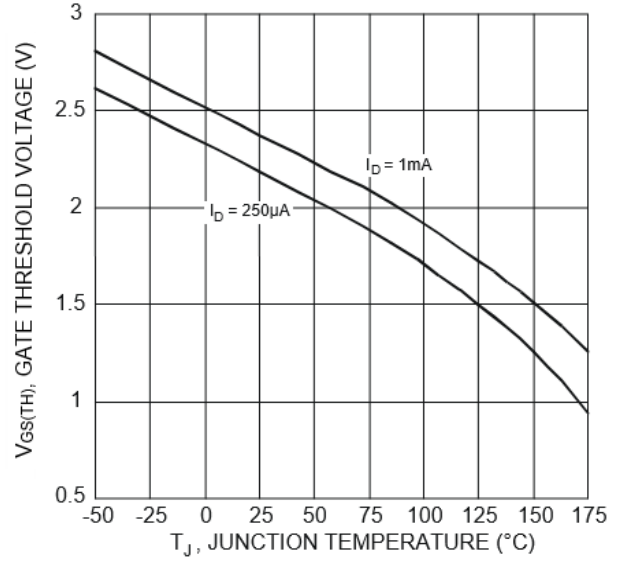


Figure 8 Gate Threshold Variation vs. Junction Temperature

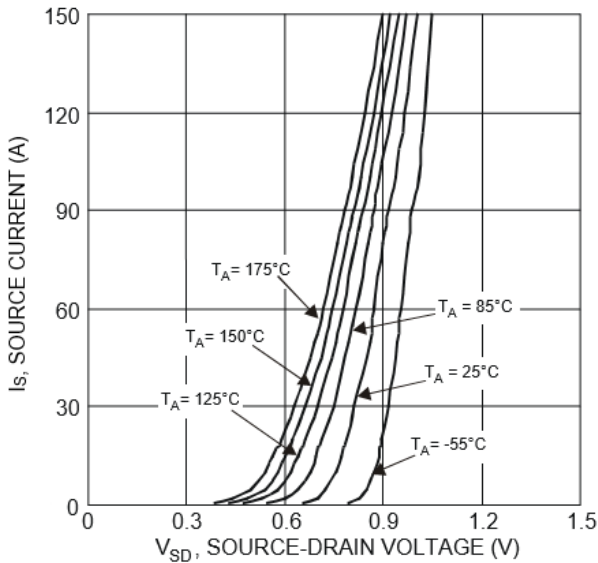


Figure 9 Diode Forward Voltage vs. Current

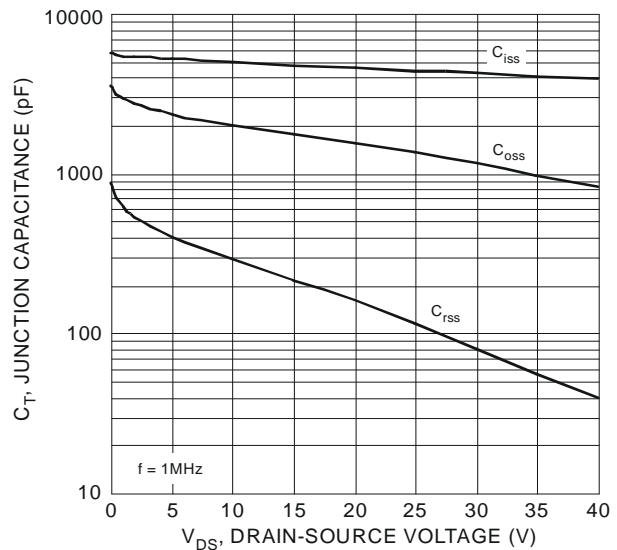


Figure 10 Typical Junction Capacitance

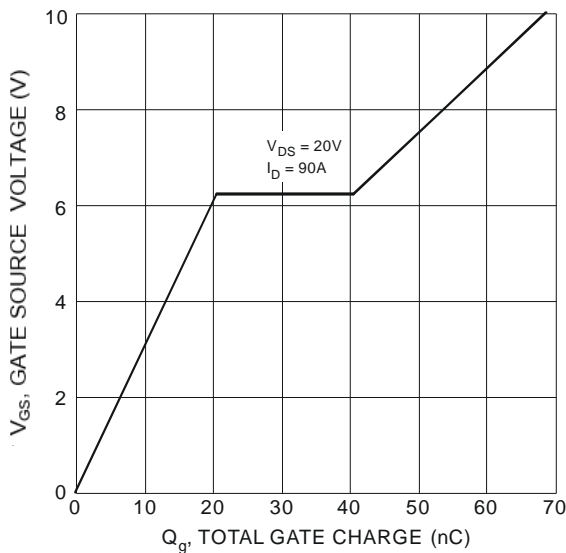


Figure 11 Gate Charge

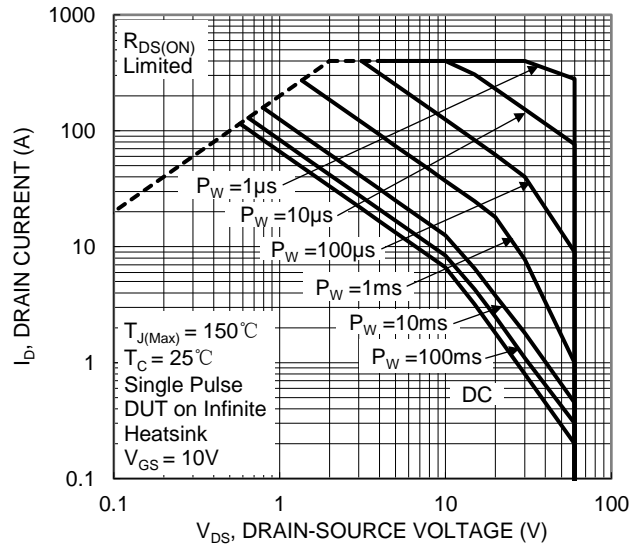


Figure 12 SOA, Safe Operation Area

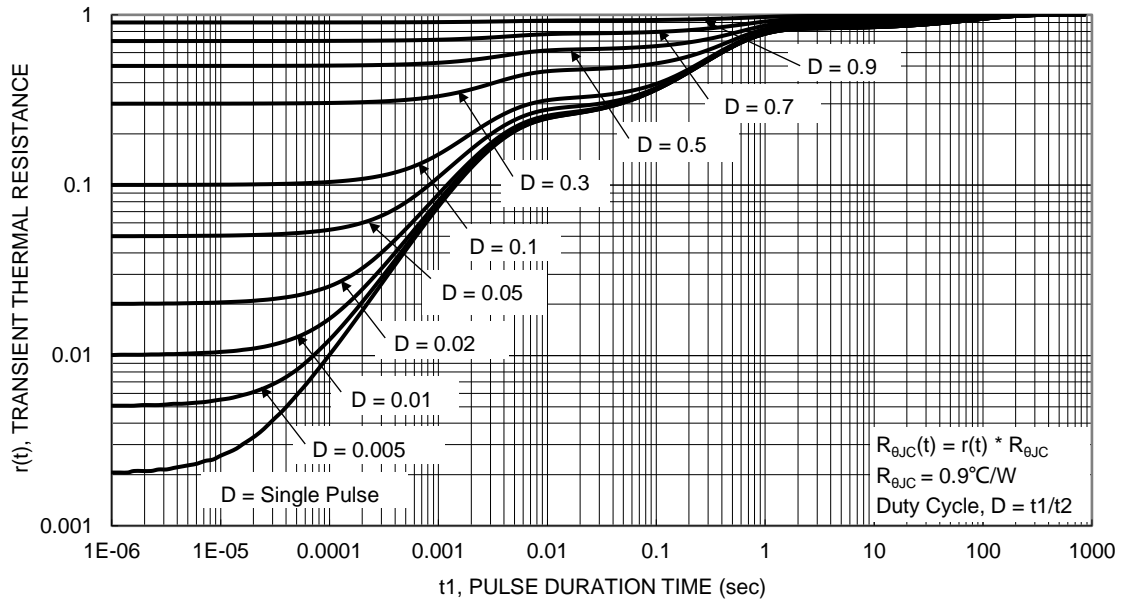
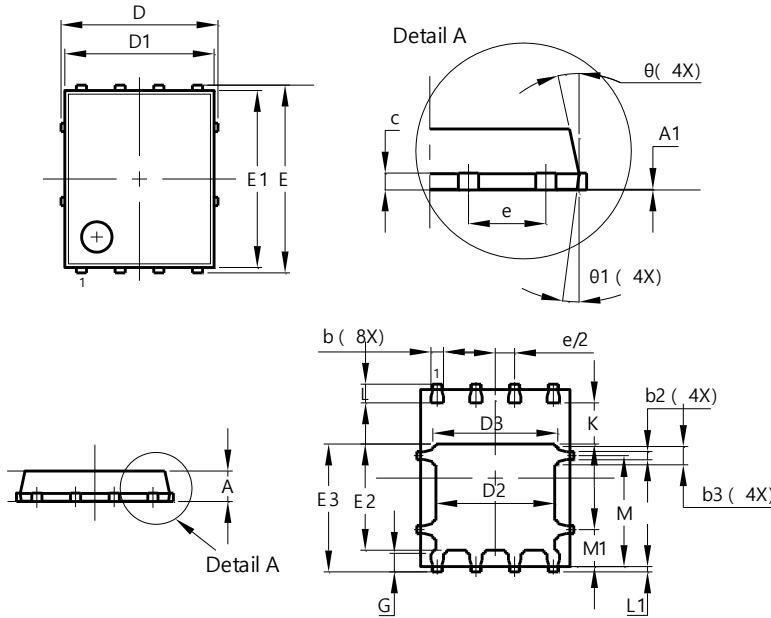


Figure 13. Transient Thermal Resistance

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI5060-8**

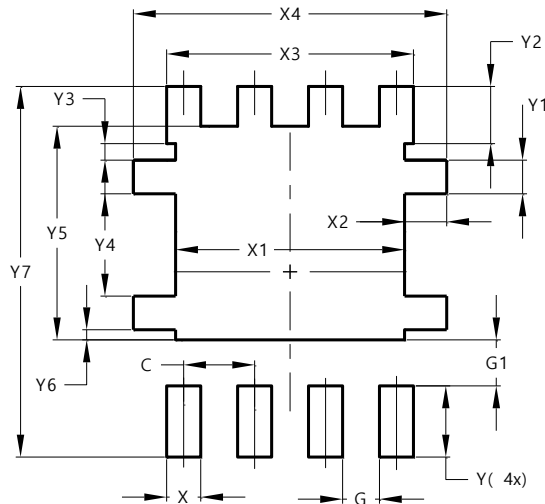


| PowerDI5060-8        |          |       |       |
|----------------------|----------|-------|-------|
| Dim                  | Min      | Max   | Typ   |
| A                    | 0.90     | 1.10  | 1.00  |
| A1                   | 0.00     | 0.05  | -     |
| b                    | 0.33     | 0.51  | 0.41  |
| b2                   | 0.200    | 0.350 | 0.273 |
| b3                   | 0.40     | 0.80  | 0.60  |
| c                    | 0.230    | 0.330 | 0.277 |
| D                    | 5.15 BSC |       |       |
| D1                   | 4.70     | 5.10  | 4.90  |
| D2                   | 3.70     | 4.10  | 3.90  |
| D3                   | 3.90     | 4.30  | 4.10  |
| E                    | 6.15 BSC |       |       |
| E1                   | 5.60     | 6.00  | 5.80  |
| E2                   | 3.28     | 3.68  | 3.48  |
| E3                   | 3.99     | 4.39  | 4.19  |
| e                    | 1.27 BSC |       |       |
| G                    | 0.51     | 0.71  | 0.61  |
| K                    | 0.51     | -     | -     |
| L                    | 0.51     | 0.71  | 0.61  |
| L1                   | 0.100    | 0.200 | 0.175 |
| M                    | 3.235    | 4.035 | 3.635 |
| M1                   | 1.00     | 1.40  | 1.21  |
| $\theta$             | 10°      | 12°   | 11°   |
| $\theta1$            | 6°       | 8°    | 7°    |
| All Dimensions in mm |          |       |       |

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI5060-8**



| Dimensions | Value (in mm) |
|------------|---------------|
| C          | 1.270         |
| G          | 0.660         |
| G1         | 0.820         |
| X          | 0.610         |
| X1         | 4.100         |
| X2         | 0.755         |
| X3         | 4.420         |
| X4         | 5.610         |
| Y          | 1.270         |
| Y1         | 0.600         |
| Y2         | 1.020         |
| Y3         | 0.295         |
| Y4         | 1.825         |
| Y5         | 3.810         |
| Y6         | 0.180         |
| Y7         | 6.610         |

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